

Atty. Dkt. No. AMAT/1931/CALB/COPPER/PJS

## RECEIVED

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

JUL 31 2001

In re Application of:

Chen et al.

Serial No.: 08/856,116

Confirmation No.: 2582

Filed:

May 14, 1997

For:

RELIABILITY BARRIER INTEGRATION FOR CU

**APPLICATION** 

Assistant Commissioner for Patents Washington, D.C. 20231

Dear Sir:

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TECHNOLOGY CENTER 2800

Group Art Unit: 2814

Examiner: G. Peralta

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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited on July 24, 2001, with the United States Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231.

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## **RESPONSE TO OFFICE ACTION DATED APRIL 25, 2001**

In response to the Office Action dated April 25, 2001, having a shortened statutory period for response set to expire on July 25, 2001, please enter the following amendments and reconsider the claims pending in the application for reasons discussed below.

## IN THE CLAIMS:

Please amend the following claims:

- 15. (Fourth Amendment) A method of filling a feature in a dielectric layer, comprising:
  - a) depositing a first barrier layer over a blanket dielectric layer;
- b) forming a feature through the first barrier layer and the dielectric layer to expose an underlayer;
- c) depositing a second barrier layer on a bottom and sidewalls in the feature;

